

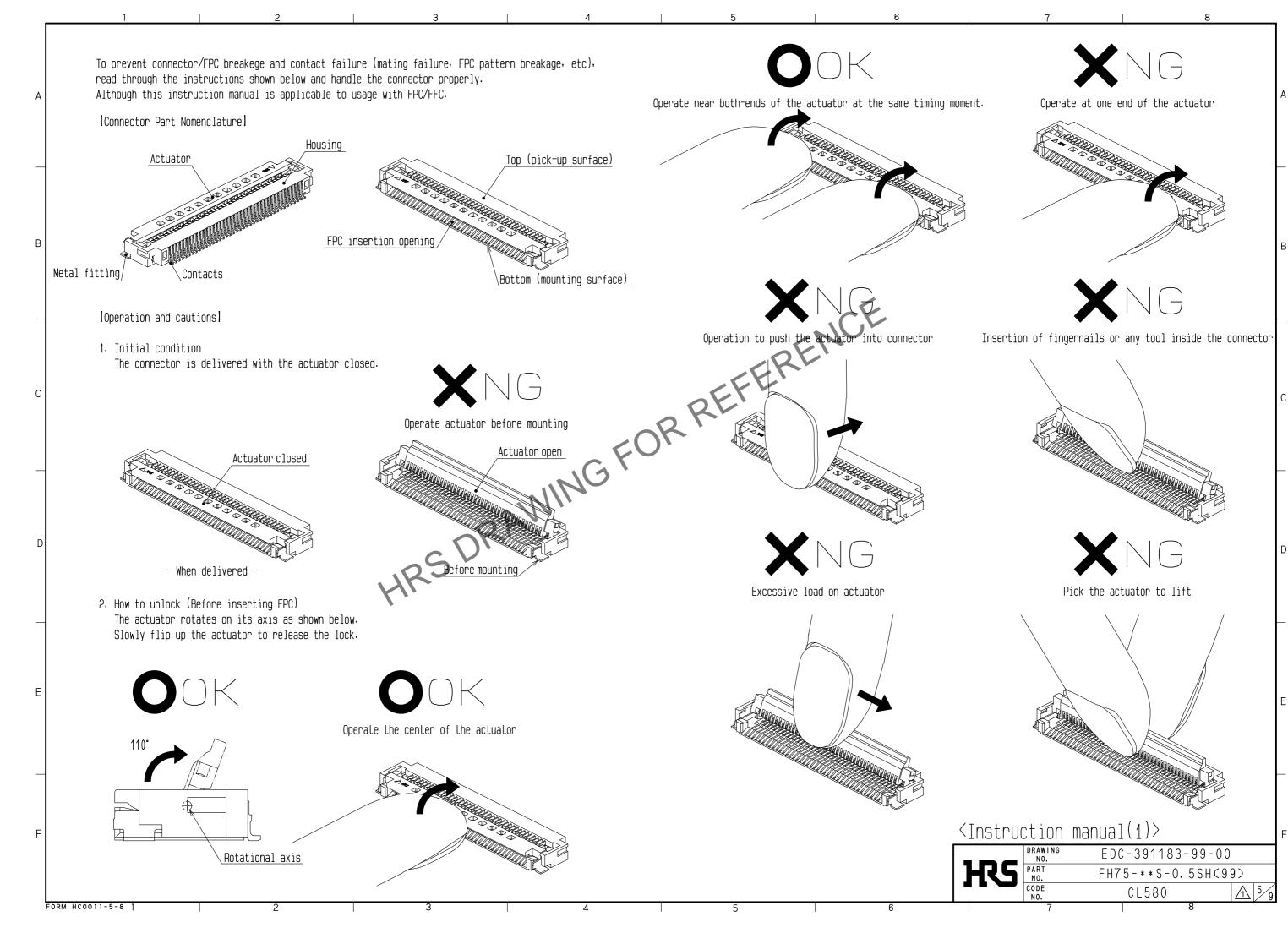
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<u> </u>	Part No.	Code Number	Number of	Dimension of connector, PCB mounting pattern, stencil pattern and FPC/FFC Dimension of drawing for packing													
			contacts	Α	В	С	D	Е	F	G	Н	J	K	L	М	Р	Q
	FH75-8S-0.5SH(99)		8	8.3	3.5	4.57	6.55	8.3	6.1	6.1	4.5	11.5	24	_	9.6	25.4	29.4
	FH75-10S-0.5SH(99)		10	9.3	4.5	5.57	7.55	9.3	7.1	7.1	5.5	11.5	24	_	10.6	25.4	29.4
	FH75-15S-0.5SH(99)		15	11.8	7.0	8.07	10.05	11.8	9.6	9.6	8.0	11.5	24	_	13.1	25.4	29.4
	FH75-30S-0.5SH(99)		30	19.3	14.5	15.57	17.55	19.3	17.1	17.1	15.5	20.2	44	40.4	20.6	45.4	49.4
	FH75-40S-0.5SH(99)	CL0580-5300-0-99	40	24.3	19.5	20.57	22.55	24.3	22.1	22.1	20.5	20.2	44	40.4	25.6	45.4	49.4
	FH75-50S-0.5SH(99)		50	29.3	24.5	25.57	27.55	29.3	27.1	27.1	25.5	20.2	44	40.4	30.6	45.4	49.4
	FH75-60S-0.5SH(99)		60	34.3	29.5	30.57	32.55	34.3	32.1	32.1	30.5	26.2	56	52.4	35.6	61.4	57.4
	FH75-68S-0.5SH(99)		68	38.3	33.5	34.57	36.55	38.3	36.1	36.1	34.5	26.2	56	52.4	39.6	61.4	57.4
	FH75-80S-0.5SH(99)		80	44.3	39.5	40.57	42.55	44.3	42.1	42.1	40.5	34.2	72	68.4	45.6	73.4	77.4

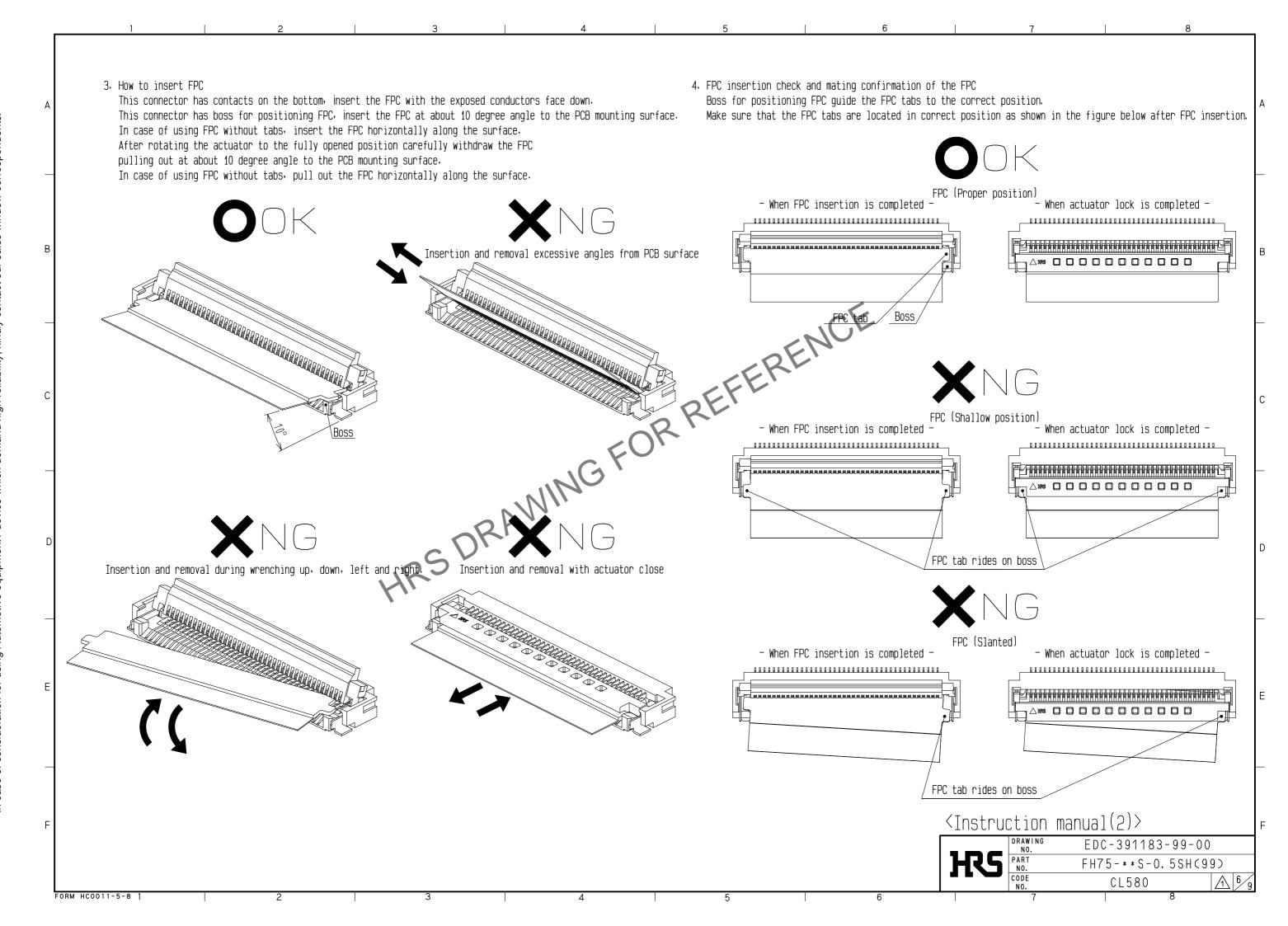
*The products without code number are currently under planning.

Please contact Hirose for detailed information about product variation.

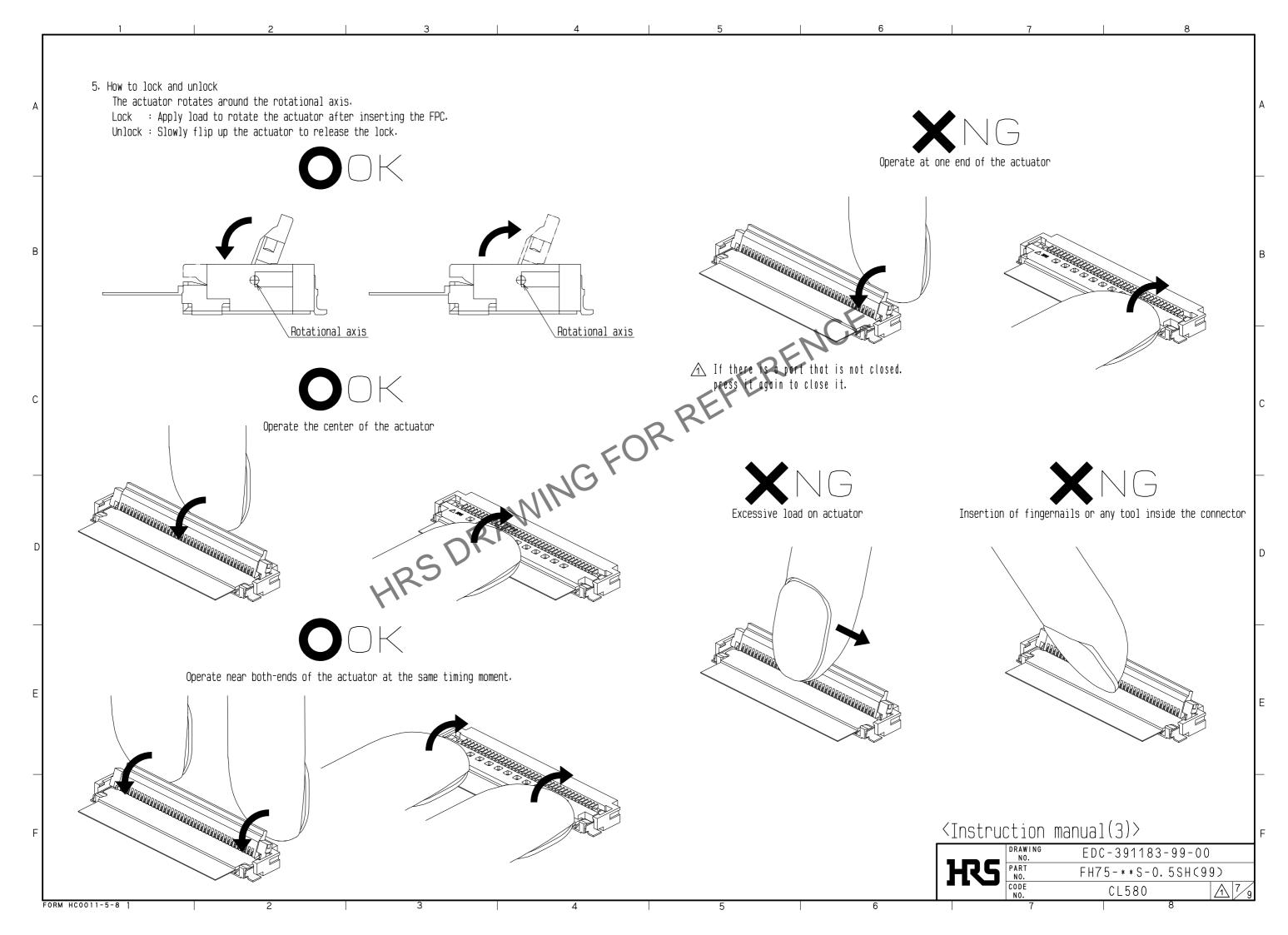
PART | CDC - 391183 - 99 - 00 | PART | FH75 - * * S - 0. 5 SH (99) | CDE | CL580 | A 4 9

FORM HC0011-5-8 1 2 3 4 5









FORM HC0011-5-8

| Instructions for PCB layout Please design a PCB layout not to apply load to connector and FPC. [Cautions] - When fixing FPC after FPC cabling, avoid pulling FPC, and route the wire FPC with slack. In this regard, the stiffener is parallel to the PCB. - Do not mount other components touching to the FPC underneath the FPC stiffener. - Make adjustments with the FPC manufacturer for FPC bending performance and wire breakage. - Keep spaces for the actuator movement and its operation for PCB design and component layout. - Please contact Hirose incase you would like to use an FPC with a different dimension or shape than recommended. Load applied to stiffener No load applied to stiffener Stiffener (horizental) Load applied to FPC Housing or parts interfering with the FPC

Instructions for mounting on the PCBI

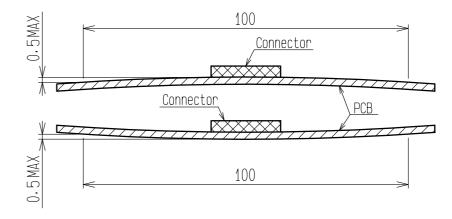
- Refer to recommended layouts for PCB, stencil pattern and FPC dimension.
- When there is silk printing etc. on the bottom of the connector, please check the mounting condition before use.
- Apply reflow temperature profile within the specified conditions. The mounting condition may change depending on the type of cream solder, manufacturer, PCB size. Please check the mounting condition before use and conditions of other mounting parts.
- Prevent warpage of PCB, the co-planarity of the connector is less than 0.1mm. but when the warpage of the PCB is large, soldering failure occurs.
- When mounting on the flexible board, please make sure to put a stiffener on the backside of the flexible board.
- We recommend a glass epoxy material with the thickness of 0.3 mm min.
- Do not add 0.5 N or greater external force when unreel or adsorb the connector etc, or it may get broken.

| Instructions for PCB handling after mounting the connector

Due to warpage of the PCB, load may be applied to the connector and it may be damaged.

- ·Splitting a large PCB into several pieces
- ·Screwing the PCB
- During the handling described above, do not exert an excessive force on the PCB.
- Otherwise, the connector may become defective.
- -The warp of a 100 mm wide PCB should be 0.5 mm or less.

The warp of PCB suffers stress on connector and the connector may become defective



[Instructions of hand soldering]

Stiffener (Diagonally)

- Do not perform hand soldering with the FPC inserted into the connector.
- Do not apply excessive heat. And soldering iron must not touch connector except terminal leads area.
- Do not supply excessive solder (flux).

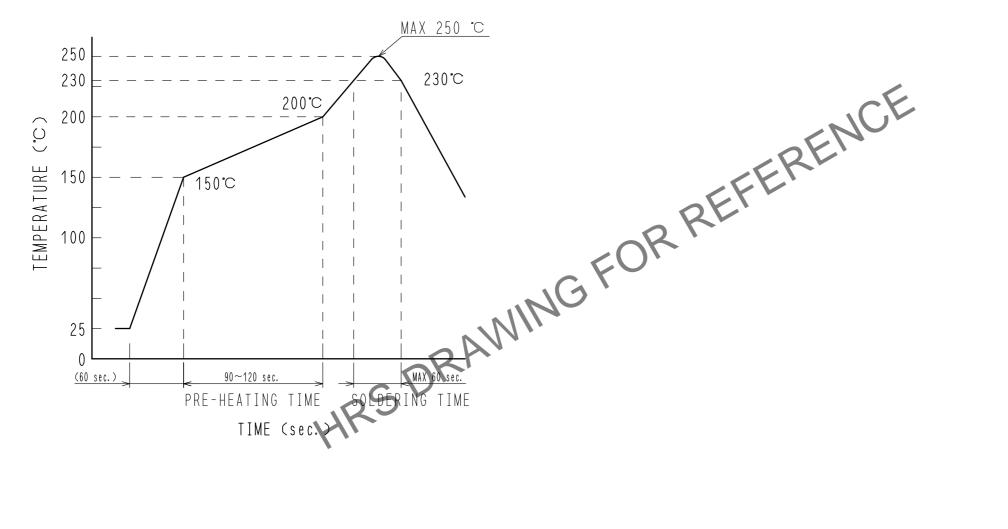
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ĸs	DRAWING NO.	EDC-391183-99-	00
	PART NO.	FH75-**S-0.5SH	(99)
	CODE	CL580	1 8/

<Instruction manual(4)>

riangle | Recommended reflow temperature profile|

The temperatures mentioned above refer to the PCB surface temperature near the connector leads. In individual applications the actual temperature may vary, depending on solder paste type.volume/thickness and board size/thickness. Consult your solder paste and equipment manufacturer for specific recommendations.

- -Reflow method:IR reflow
- -Number of reflow cycles:2 cycles MAX.



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